



## Film Capacitors

### Metallized Polypropylene Film Capacitors (MKP)

**Series/Type:** B32669  
**Date:** December 2012

**Not suitable for "across the line" applications!**

### Typical applications

- Energy storage
- Filtering

### Climatic

- Max. operating temperature: 85 °C
- Climatic category (IEC 60068-1): 40/085/21

### Construction

- Dielectric: polypropylene (PP)
- Cylindrical winding
- Insulating sleeve
- Face ends sealed with epoxy resin

### Features

- Good self-healing properties
- RoHS-compatible

### Terminals

- Axial leads, lead-free tinned
- Axial leads, insulated, tinned copper wires gathered together by a tin cover (fray), AWG 22

### Marking

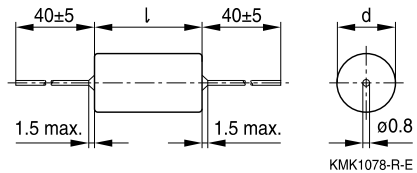
Manufacturer  
Series number  
rated capacitance (coded),  
capacitance tolerance (code letter),  
rated AC voltage, frequency, date code

### Delivery mode

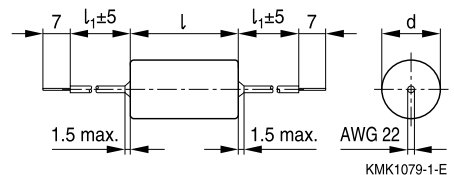
Bulk (untaped)

### Dimensional drawing

Tinned leads



Insulated leads



Dimensions in mm

When bending leads, take care to leave a clearance of 1 mm to the capacitor body.



## Overview of available types

Version	Tinned leads		Insulated leads	
Page	4		5	
$V_{RMS}$ (V AC)	250	400	250	400
$C_R$ ( $\mu F$ )				
1.0				
1.5				
2.0				
2.5				
3.0				
4.0				
5.0				
6.0				
8.0				
10				



**B32669**

**AC applications (wound)**

### Ordering codes and packing units (tinned leads)

$V_{RMS}$	$C_R$	Max. dimensions $d \times l$ mm	Ordering code (composition see below)	Untaped pcs./MOQ
V AC	$\mu F$			
250	1.0	$9.0 \times 32.0$	B32669C3105+000	1000
	1.5	$11.0 \times 32.0$	B32669C3155+000	1000
	2.0	$12.5 \times 32.0$	B32669C3205+000	800
	2.5	$14.0 \times 32.0$	B32669C3255+000	800
	3.0	$15.5 \times 32.0$	B32669C3305+000	600
	4.0	$15.0 \times 47.0$	B32669C3405+000	600
	6.0	$17.0 \times 47.0$	B32669C3605+000	400
	8.0	$19.5 \times 47.0$	B32669C3805+000	200
	10	$21.5 \times 47.0$	B32669C3106+000	200
400	1.0	$13.0 \times 32.0$	B32669B6105+000	1000
	1.5	$15.0 \times 32.0$	B32669B6155+000	800
	2.0	$19.0 \times 32.0$	B32669B6205+000	800
	2.5	$21.0 \times 32.0$	B32669B6255+000	600
	3.0	$18.0 \times 47.0$	B32669B6305+000	600
	4.0	$21.0 \times 47.0$	B32669B6405+000	400
	5.0	$22.0 \times 47.0$	B32669B6505+000	600
	6.0	$25.5 \times 47.0$	B32669B6605+000	200

MOQ = Minimum Order Quantity, consisting of 4 packing units.  
Further E series and intermediate capacitance values on request.

### Composition of ordering code

+ = Capacitance tolerance code:

K =  $\pm 10\%$

J =  $\pm 5\%$

### Ordering codes and packing units (insulated leads)

$V_{RMS}$	$C_R$	Max. dimensions $d \times l$ mm	Ordering code (composition see below)	Untaped pcs./MOQ
V AC	$\mu F$			
250	1.0	$9.0 \times 32.0$	B32669S3105+***	1000
	1.5	$11.0 \times 32.0$	B32669S3155+***	1000
	2.0	$12.5 \times 32.0$	B32669S3205+***	1000
	2.5	$14.0 \times 32.0$	B32669S3255+***	1000
	3.0	$15.5 \times 32.0$	B32669S3305+***	800
	4.0	$15.0 \times 47.0$	B32669S3405+***	800
	6.0	$17.0 \times 47.0$	B32669S3605+***	600
	8.0	$19.5 \times 47.0$	B32669S3805+***	600
400	10	$21.5 \times 47.0$	B32669S3106+***	600
	1.0	$13.0 \times 32.0$	B32669S6105+***	1000
	1.5	$15.0 \times 32.0$	B32669S6155+***	1000
	2.0	$19.0 \times 32.0$	B32669S6205+***	1000
	2.5	$21.0 \times 32.0$	B32669S6255+***	600
	3.0	$18.0 \times 47.0$	B32669S6305+***	600
	4.0	$21.0 \times 47.0$	B32669S6405+***	600
	5.0	$22.0 \times 47.0$	B32669S6505+***	600
	6.0	$25.5 \times 47.0$	B32669S6605+***	600

MOQ = Minimum Order Quantity, consisting of 4 packing units.  
Further E series and intermediate capacitance values on request.

### Composition of ordering code

+ = Capacitance tolerance code:

K =  $\pm 10\%$

J =  $\pm 5\%$

\*\*\* = Code number for lead version and length:

504 = Insulated leads (lead length 160 mm)

508 = Insulated leads (lead length 65 mm)

**B32669****AC applications (wound)****Technical data**

Operating temperature range	Max. operating temperature $T_{op,max}$	+85 °C
	Upper category temperature $T_{max}$	+85 °C
	Lower category temperature $T_{min}$	−40 °C
	Rated temperature $T_R$	+85 °C
Dissipation factor $\tan \delta$ at 20 °C (upper limit values)	$2 \cdot 10^{-3}$ at 1 kHz	
Time constant $\tau = C_R \cdot R_{ins}$ at 20 °C, rel. humidity $\leq 65\%$ (minimum as-delivered values)	2500 s	
DC test voltage	$V_R = 250$ V AC: 430 V DC, 1 s	
	$V_R = 400$ V AC: 700 V DC, 1 s	
AC test voltage	$V_R = 250$ V AC: 440 V AC, 1 s	
	$V_R = 400$ V AC: 700 V AC, 1 s	
Damp heat test Limit values after damp heat test	21 days/40 °C/93% relative humidity	
	Capacitance change $ \Delta C/C $	$\leq 3\%$
	Dissipation factor change $\Delta \tan \delta$	$\leq 0.5 \cdot 10^{-3}$ (at 1 kHz) $\leq 1.0 \cdot 10^{-3}$ (at 10 kHz)
	Time constant $\tau = C_R \cdot R_{ins}$	$\geq 50\%$ of minimum as-delivered values
Pulse handling capability (rate of voltage rise $V_{pp}/\tau$ )	$\leq 10$ V/ $\mu$ s	

**Permissible AC voltage  $V_{RMS}$  versus frequency  $f$** 

Values can be obtained on request. In specific cases please provide a scaled voltage/ time graph and state operating conditions.

## Mounting guidelines

### 1 Soldering

#### 1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/–0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

#### 1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A.

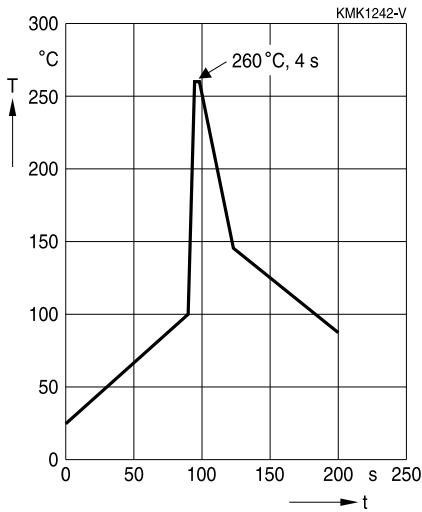
Conditions:

Series	Solder bath temperature	Soldering time
MKT boxed (except 2.5 × 6.5 × 7.2 mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP		
MKP (lead spacing > 7.5 mm)		
MKT boxed (case 2.5 × 6.5 × 7.2 mm)		5 ±1 s
MKP (lead spacing ≤ 7.5 mm)		< 4 s
MKT uncoated (lead spacing ≤ 10 mm) insulated (B32559)		recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)



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**AC applications (wound)**



Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
$\tan \delta$	As specified in sectional specification



### 1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature  $T_{\max}$ . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
  - diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
  - MKP/MFP 110 °C
  - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

#### Uncoated capacitors

For uncoated MKT capacitors with lead spacings  $\leq 10$  mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering



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AC applications (wound)

## Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

**B32669****AC applications (wound)****Symbols and terms**

Symbol	English	German
$\alpha$	Heat transfer coefficient	Wärmeübergangszahl
$\alpha_C$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
$\beta_C$	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
$C_R$	Rated capacitance	Nennkapazität
$\Delta C$	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
$\Delta t$	Time interval	Zeitintervall
$\Delta T$	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta \tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
$\Delta V$	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
$f_1$	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
$f_2$	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
$f_r$	Resonant frequency	Resonanzfrequenz
$F_D$	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
$F_T$	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
$I_C$	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)

Symbol	English	German
$I_{RMS}$	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
$i_z$	Capacitance drift	Inkonstanz der Kapazität
$k_0$	Pulse characteristic	Impulskennwert
$L_S$	Series inductance	Serieninduktivität
$\lambda$	Failure rate	Ausfallrate
$\lambda_0$	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase
$\lambda_{test}$	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
$P_{diss}$	Dissipated power	Abgegebene Verlustleistung
$P_{gen}$	Generated power	Erzeugte Verlustleistung
$Q$	Heat energy	Wärmeenergie
$\rho$	Density of water vapor in air	Dichte von Wasserdampf in Luft
$R$	Universal molar constant for gases	Allg. Molarkonstante für Gas
$R$	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
$R_i$	Internal resistance	Innenwiderstand
$R_{ins}$	Insulation resistance	Isolationswiderstand
$R_P$	Parallel resistance	Parallelwiderstand
$R_S$	Series resistance	Serienwiderstand
$S$	severity (humidity test)	Schärfegrad (Feuchtetest)
$t$	Time	Zeit
$T$	Temperature	Temperatur
$\tau$	Time constant	Zeitkonstante
$\tan \delta$	Dissipation factor	Verlustfaktor
$\tan \delta_D$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
$\tan \delta_P$	Parallel component of dissipation factor	Parallelanteil des Verlustfaktors
$\tan \delta_S$	Series component of dissipation factor	Serienanteil des Verlustfaktors
$T_A$	Ambient temperature	Umgebungstemperatur
$T_{max}$	Upper category temperature	Obere Kategorietemperatur
$T_{min}$	Lower category temperature	Untere Kategorietemperatur
$t_{OL}$	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
$T_{op}$	Operating temperature	Betriebstemperatur
$T_R$	Rated temperature	Nenntemperatur
$T_{ref}$	Reference temperature	Referenztemperatur
$t_{SL}$	Reference service life	Referenz-Lebensdauer
$V_{AC}$	AC voltage	Wechselspannung



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**AC applications (wound)**

Symbol	English	German
$V_C$	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
$V_{CD}$	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
$V_{ch}$	Charging voltage	Ladespannung
$V_{DC}$	DC voltage	Gleichspannung
$V_{FB}$	Fly-back capacitor voltage	Spannung (Flyback)
$V_i$	Input voltage	Eingangsspannung
$V_o$	Output voltage	Ausgangssspannung
$V_{op}$	Operating voltage	Betriebsspannung
$V_p$	Peak pulse voltage	Impuls-Spitzenspannung
$V_{pp}$	Peak-to-peak voltage Impedance	Spannungshub
$V_R$	Rated voltage	Nennspannung
$\hat{V}_R$	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
$V_{RMS}$	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
$V_{SC}$	S-correction voltage	Spannung bei Anwendung "S-correction"
$V_{sn}$	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
$Z$	Impedance	Scheinwiderstand
$e$	Lead spacing	Rastermaß

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The following applies to all products named in this publication:

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